PCN Nun			20180531002		PCN Date:	ate: June 1, 2018				
Title: Datasheet for bq27546-G1										
Cu	stome	r Contact:	PCN Manag	er		E.	De	pt:	Quality Services	
Ch	ange 1									
	Assembly Site				Design			Wafer Bump Site		
Assembly Process				\boxtimes					Bump Material	
Assembly Materials					Part number change	4			Bump Process	
Mechanical Specification					Test Site	┥┟			Fab Site	
Packing/Shipping/Label			Labeling		Test Process				Fab Materials	
					otification Details			Wafer Fab Process		
Description of Change:										
Texas Instruments Incorporated is announcing an information only notification.										
The product datasheet(s) is being updated as summarized below. The following change history provides further details.										
TEXAS INSTRUMENTS bq27546-G1 SLUSC53B -MAY 2015-REVISED MAY 2018										
Changes from Revision A (December 2015) to Revision B Page										
Changed Simplified Schematic										
The datasheet number will be changing.										
Device Family				<u> </u>	Change From:	ge From:		Change To:		
bq27546-G1				SLUSC53A	SLUSC53A			SLUSC53B		
These changes may be reviewed at the datasheet links provided.										
http://www.ti.com/product/bq27546-G1										
Reason for Change:										
To accurately reflect device characteristics.										
Anticipated impact on Fit, Form, Function, Quality or Reliability (positive / negative):										
No anticipated impact. This is a specification change announcement only. There are no changes to the actual device.										
Changes to product identification resulting from this PCN:										
None.										
Product Affected:										
B	Q27546	6YZFR-G1	BQ27546	YZF	T-G1					
For questions regarding this notice, e-mails can be sent to the regional contacts shown below										

or your local Field Sales Representative.

Location	E-Mail
USA	PCNAmericasContact@list.ti.com
Europe	PCNEuropeContact@list.ti.com
Asia Pacific	PCNAsiaContact@list.ti.com
Japan	PCNJapanContact@list.ti.com